Docket No.

240586US2/hc

IN THE UNITED STATE PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF:

Takashi IPPOSHI

SERIAL NO: FILED: 10/623,557

July 22, 2003

GAU:

EXAMINER:

FOR:

SEMICONDUCTOR DEVICE

INFORMATION DISCLOSURE STATEMENT UNDER 37 CFR 1.97

COMMISSIONER FOR PATENTS ALEXANDRIA, VIRGINIA 22313

SIR:

Applicant(s) wish to disclose the following information.

REFERENCES

The applicant(s) wish to make of record the references listed on the attached form PTO-1449. Copies of the listed references are attached, where required, as are either statements of relevancy or any readily available English translations of pertinent portions of any non-English language references.

☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

RELATED CASES

Attached is a list of applicant's pending application(s) or issued patent(s) which may be related to the present application. A copy of the patent(s), together with a copy of the claims and drawings of the pending application(s) is attached along with PTO 1449.

☐ A check or credit card payment form is attached in the amount required under 37 CFR §1.17(p).

CERTIFICATION

Each item of information contained in this information disclosure statement was first cited in a communication from a foreign patent office in a counterpart foreign application not more than three months prior to the filing of
this statement.

□ No item of information contained in this information disclosure statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned, having made reasonable inquiry, was known to any individual designated in 37 CFR §1.56(c) more than three months prior to the filing of this statement.

DEPOSIT ACCOUNT

Please charge any additional fees for the papers being filed herewith and for which no check or credit card payment is enclosed herewith, or credit any overpayment to deposit account number <u>15-0030</u>. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.

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22850

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STATEMENT OF RELEVANCY

All of the references on Form 1449 are discussed in the specification.

Form PTO 1449	U.S. DEPARTMENT OF COMMERCE			ATTY DOCKET NO.		SERIAL NO.			
(Modified)		PATENT AND TRA		240586US2		10/623,557			
(DE)			APPLICANT						
LIST OF REFERENCES CITED BY APPLICANT			Takashi IPPOSHI						
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		FIGU		U.S. PATENT DOCUMENTS					
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		DOCUMENT NUMBER	DATE	COUNTRY	COUNTRY		TRANSLATION		
	AO	2002-134374	05/10/2002 JAPAN (corr. USSN 09/930,202) 12/22/1995 JAPAN (with English extract)			YES	S NO		
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	Y. HIRANO, et al., IEEE International SOI Conference, pages 131-132, "BULK-LAYOUT-COMPATIBLE 0.18µm SOI-CMOS TECHNOLOGY USING BODY-FIXED PARTIAL TRENCH ISOLATION (PTI)", October 1999								
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	AY	L-J. HUANG, et al., Symposium on VLSI Technology Digest of Technical Papers, pages 57-58, "CARRIER MOBILITY ENHANCEMENT IN STRAINED Si-On-INSULATOR FABRICATED BY WAFER BONDING", 2001							
	AZ				Addi	tional Pefe	vences sheet(s) attached		
Examiner		<u> </u>			Additional References sheet(s) attached Date Considered				
*Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.									
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